

PHASE 1: 6T SRAM CELL

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6-transistor (6T) SRAM cell is the fundamental storage element in static RAM.

It stores a single bit of data ("0" or "1") using two cross-coupled CMOS inverters, which maintain a stable bistable state as long as power is supplied.

Each cell can be **read** or **written** through two **access transistors**, controlled by the **word line (WL)** and connected to the **bit lines (BL, BLB)**.

COMPONENTS

WORDLINE (WL)

Its used to set the operation the SRAM performs. It is used to enable/disable the access transistors.

It controls all the cells in a single row of the memory array.

- When **WL = 1 (activated)**:
 - Access transistors turn ON.
 - The cell can **read** or **write** through the bit lines.
- When **WL = 0 (deactivated)**:
 - Access transistors turn OFF.
 - Cell is **isolated** from bit lines. It retains its data.

BITLINE (BL and ~BL)

They're used to read from or write to the cell. These two lines carry **opposite logic levels** during both **read** and **write** operations.

They serve as **bidirectional** data paths:

- **During a read:** They act as **sensing lines**.
- **During a write:** They act as **data input lines**.

There are 2 Bit Lines as it helps with performing Read and Write operations faster.

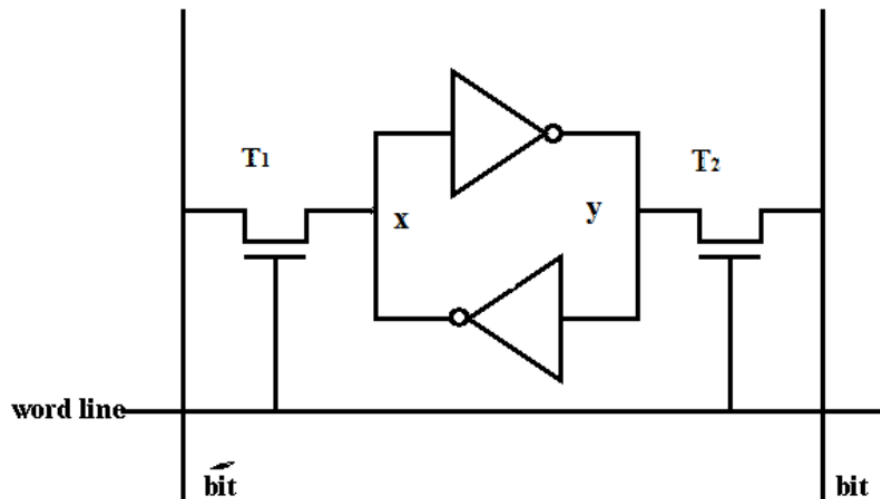
ACCESS TRANSISTORS (M5, M6)

They're used to connect or disconnect the cell from the Bitlines during read/write.

When the **word line (WL)** is:

- **LOW (0):**
 - M5 and M6 are OFF → cell is isolated.
 - Data is **retained** internally (Hold mode).
- **HIGH (1):**
 - M5 and M6 are ON → cell is connected to Bitlines.
 - Allows **read or write** operation, depending on Bitline voltages.

CROSS COUPLED INVERTERS



Each inverter consists of a **pull-up pMOS** and a **pull-down nMOS** transistor:

M2, M4 are PULL UP PMOS and M1, M3 are PULL DOWN NMOS.

INV1 is made of M1 and M2. INV2 is made of M3 and M4.

These two inverters are **cross-coupled**:

- The **output of INV1 (Q)** connects to the **input of INV2**,
- The **output of INV2 (\bar{Q})** connects to the **input of INV1**.

This cross-coupling creates a **positive feedback loop** that makes the circuit **bistable**, meaning:

- It can **permanently stay** in either of two stable states as long as power is provided:
 - $Q = 1, \bar{Q} = 0 \rightarrow$ stores logic 1
 - $Q = 0, \bar{Q} = 1 \rightarrow$ stores logic 0

MODES

IDLE

Stored data is retained as long as power is supplied to the inverters.

This mode is entered when -

- $WL = 0 \rightarrow$ access transistors (M5, M6) are OFF.

- The two cross-coupled inverters reinforce each other:
if $Q = 1 \rightarrow Q_{\text{bar}} = 0$, and vice versa.
- Because there is **no current path** to BL or \sim BL the stored data is retained indefinitely.

READ

In this mode we can read what value is stored in the SRAM cell.

To perform this operation -

- Word Line: **WL = 1** (Access transistors ON)
- Bit Lines: **BL and \sim BL precharged to VDD**
- Sense Amplifier: Enabled after a short delay

STEPS

- **Precharge :**

Both BL and \sim BL are charged to VDD before WL is activated.

- **Word Line Activated:**

WL = 1 \rightarrow Access transistors connect internal nodes Q and Q_{bar} to BL and \sim BL respectively.

- **Small Differential Development:**

- If cell stores **Q = 1, $Q_{\text{bar}} = 0$:**
 - The node Q (1) connects to BL \rightarrow BL remains close to VDD.
 - The node Q_{bar} (0) connects to \sim BL \rightarrow \sim BL starts to **discharge slightly** through M5 and M6.
- If cell stores **Q = 0, $Q_{\text{bar}} = 1$** , the opposite occurs:
 - BL discharges slightly; \sim BL remains high.

- **Sensing:**

- The **sense amplifier** detects which line is slightly lower.
- Since the difference is small , differential sensing allows **high-speed and low-power** read.

- **Restoring:**

- Once data is read, WL is turned off again.
- Precharge circuits restore both BL and \sim BL to VDD for the next cycle.

WRITE

In this mode we can write onto the SRAM a bit value.

To perform this operation -

- WL = 1 → Access transistors ON
- Bit lines are actively driven by the **write driver circuit**:
 - To write '1': BL = 1 (VDD), \sim BL = 0 (GND)
 - To write '0': BL = 0 (GND), \sim BL = 1 (VDD)

STEPS

- **Setup Bit Lines:**
 - Write drivers force complementary voltages on BL and \sim BL.
 - Example: To write 0 → BL = 0, \sim BL = 1
- **Activate Word Line:**
 - WL = 1 → Access transistors connect bit lines to storage nodes.
- **Overpower and Flip the Cell:**
 - The node connected to BL = 0 starts to discharge.
 - The cross-coupled feedback ensures that once one side starts dropping, the opposite side rises quickly.
 - The inverters **regenerate** the new stable state (new data stored).
- **Finish Write:**
 - WL is turned off → Access transistors OFF.
 - The bit lines are returned to precharge state.

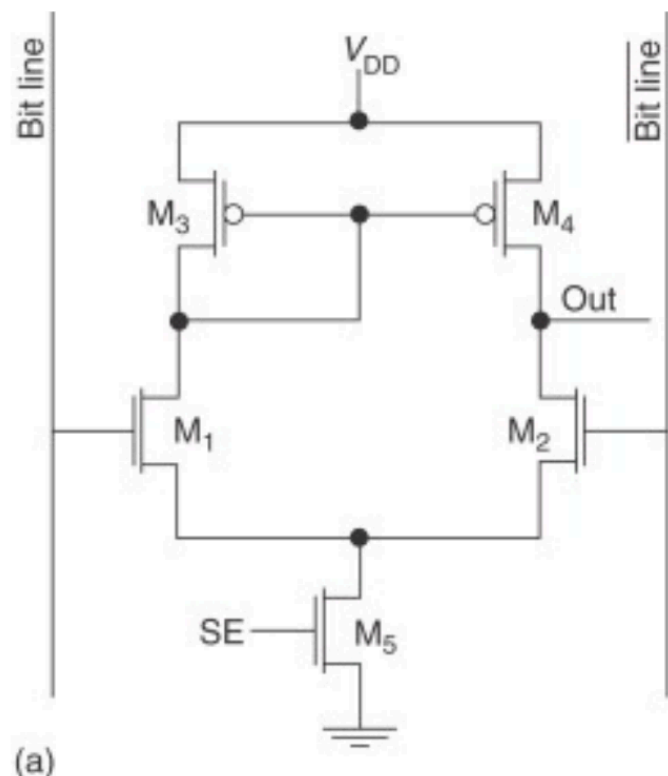
PRECHARGING

Before every **read or write**, both **bit lines (BL and \sim BL)** are brought to a **known voltage level**.

Precharge sets both Bitlines to a known voltage (usually V_{DD}) so the sense amplifier can reliably detect the tiny voltage difference during a Read. It also ensures Bitlines can swing fully during Writes and prevents floating voltages when idle.

SENSE AMPLIFIER

The **Sense Amplifier** is a **small, high-speed differential amplifier** used during the **read operation** in SRAM.



Its used to recognize which bit is stored in the READ operation.

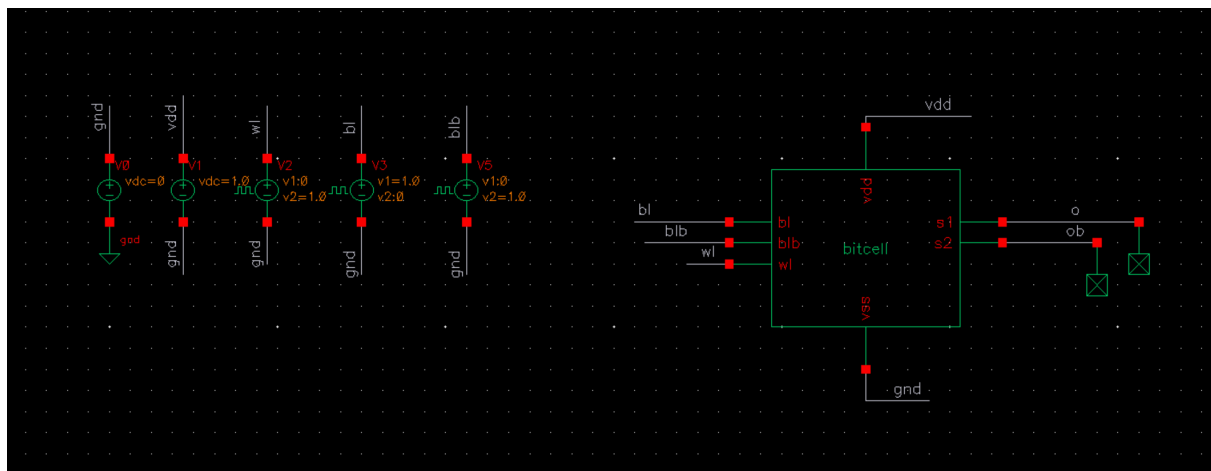
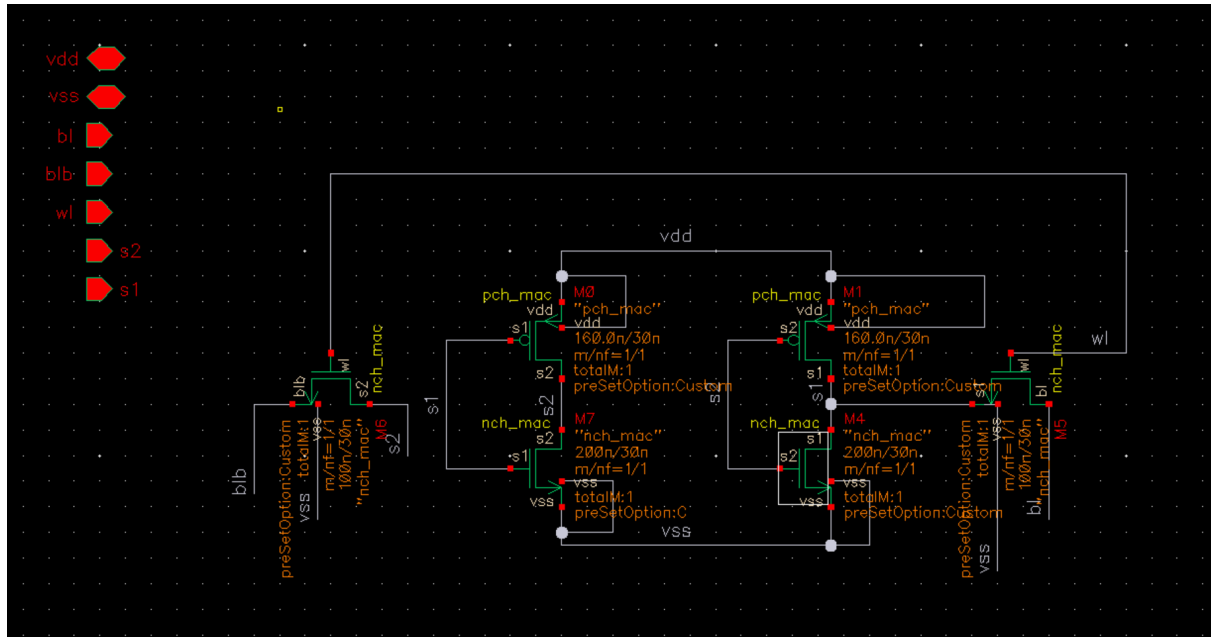
When a voltage difference develops across its terminals, it amplifies it and based on whether it is positive or negative it can quickly identify if 0 or 1 was stored.

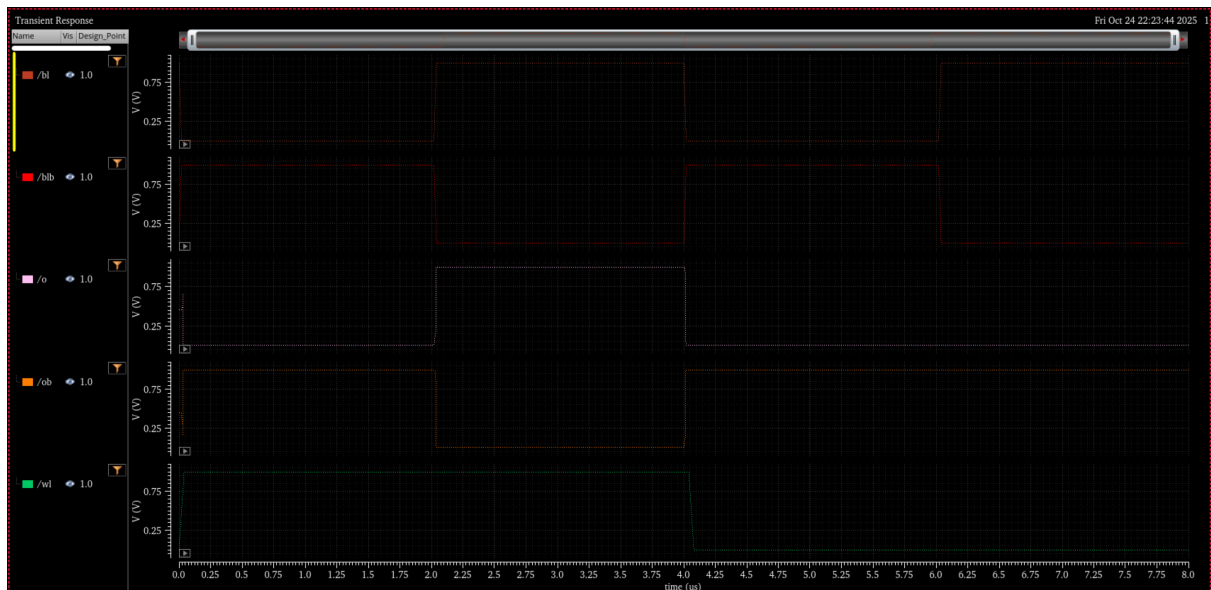
- **0 stored:** BL \rightarrow discharges slightly \rightarrow SA detects BL < \sim BL \rightarrow outputs 0
- **1 stored:** \sim BL \rightarrow discharges slightly \rightarrow SA detects BL > \sim BL \rightarrow outputs 1

It mainly used because -

- Without differential sensing, detecting small voltage swings would be too slow.
- Positive feedback in the SA ensures **full rail-to-rail swing**.

W/L RATIOS (28 TSMC)

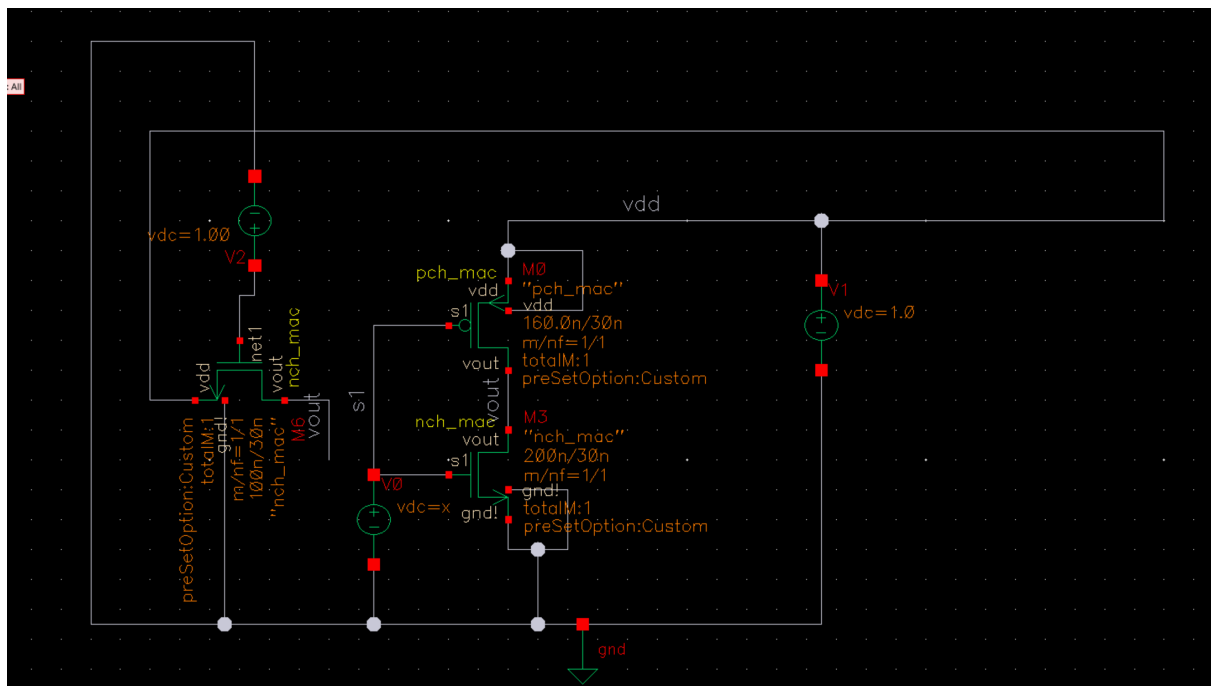


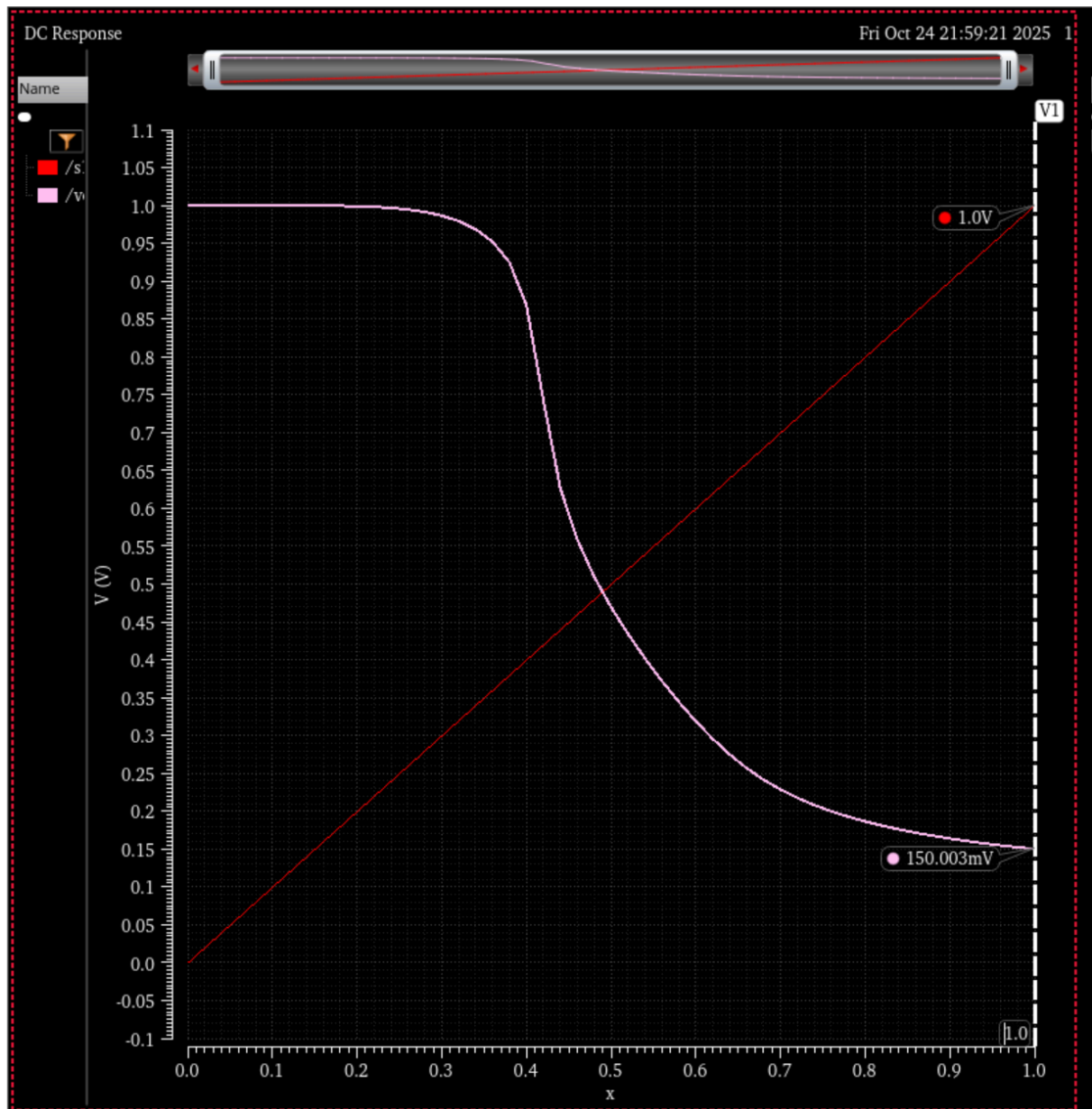


The plots show the **transient voltage responses** of the word line (WL), bit lines (BL and BL_B), and the output node (Q) during **read and write operations** for the chosen W/L sizing in the 28 nm TSMC process.

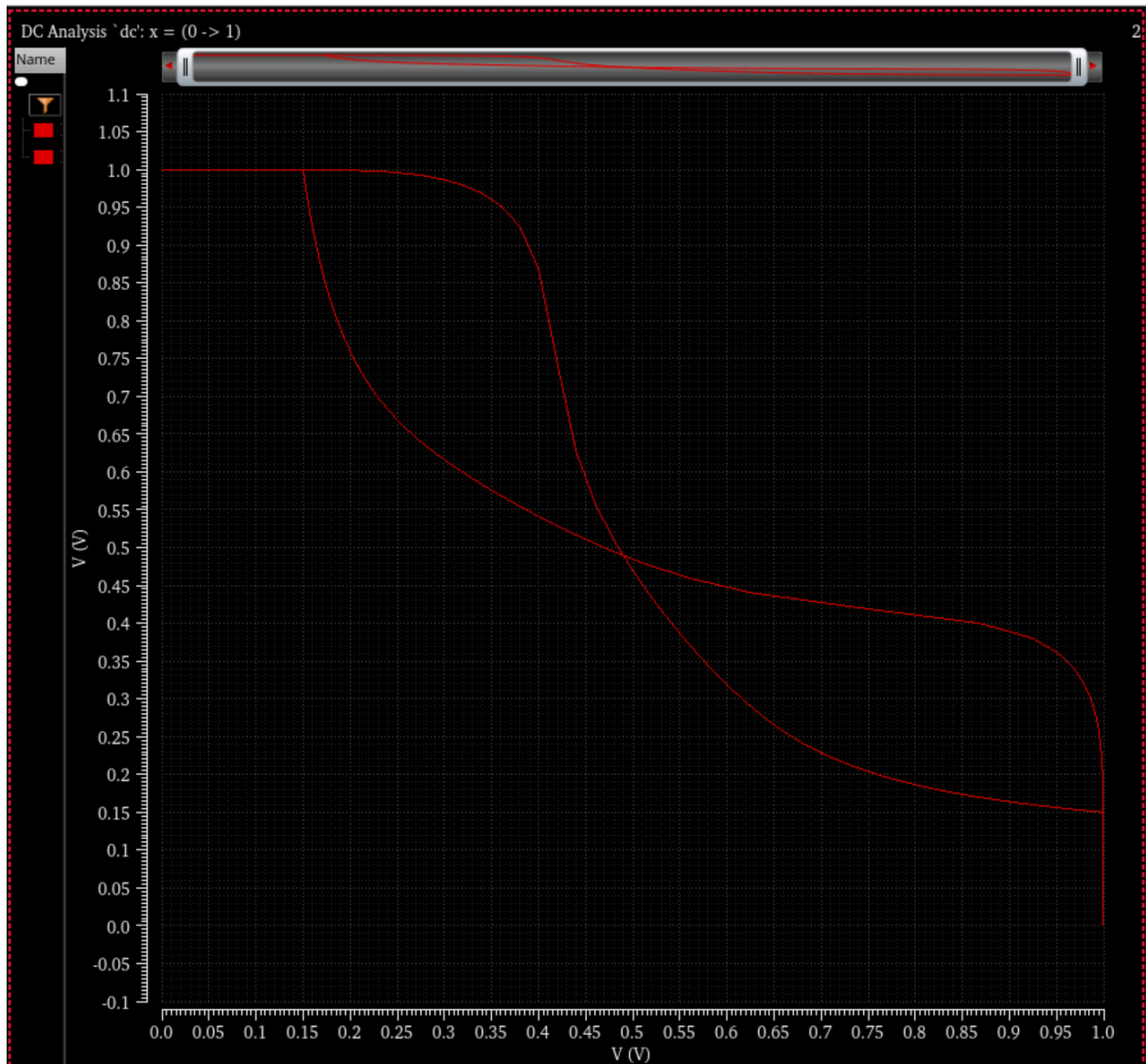
NOISE MARGINS

Read Static Noise Margin (SNM)



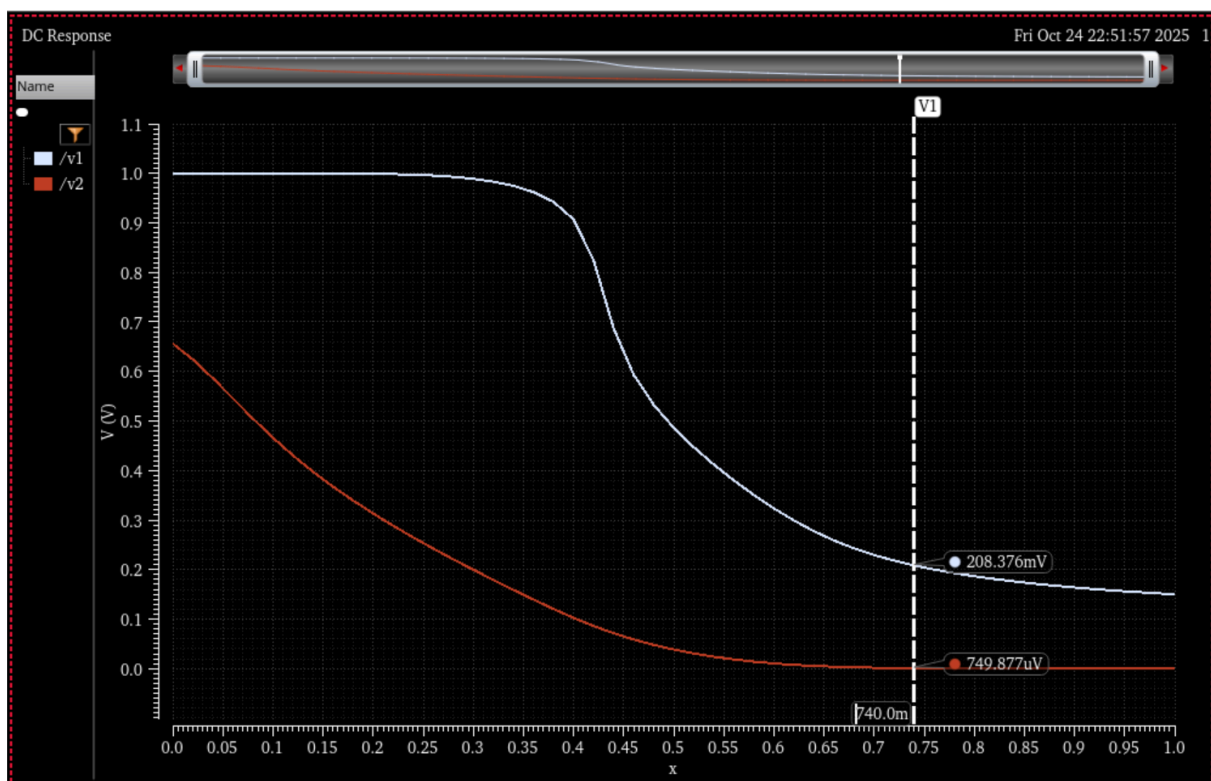
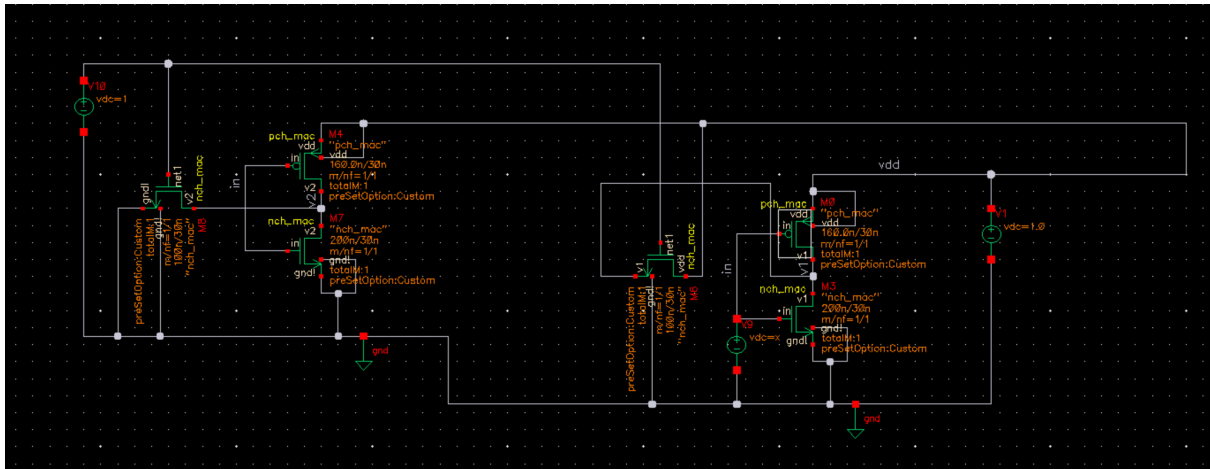


This plot shows the **voltage transfer characteristics (VTC)** of the two cross-coupled inverters that form the 6T SRAM cell. One inverter's VTC is mirrored and overlapped with the other to form a **butterfly-shaped curve**.



- The **Static Noise Margin (SNM)** is defined as the **length of the side of the largest possible square** that can fit between the two inverter curves.
- It represents the **maximum DC noise voltage** the cell can tolerate without flipping its stored bit during idle/read.
- The point where both inverter curves **intersect** being close to **VDD/2 (≈ 0.9 V for VDD = 1.8 V)** indicates that both inverters have **equal strength** and **balanced noise immunity**.
- The butterfly curve is symmetric, meaning the cell can tolerate equal noise margins for both '0' and '1' states — ideal for reliable operation.
- The worst-case voltage rise in the SRAM cell during a read is 150.003mV.

Write Noise Margin (WNM)



- During a write operation, one of the bitlines is pulled low while $WL = 1$.
- The WNM is the **minimum Bit Line voltage difference** required to successfully **flip the stored value** during a write operation.
- It depends on the strength of the **access transistors** and the **pull-up PMOS**.
 - Stronger access \rightarrow higher write-ability.
 - Stronger pull-up \rightarrow harder to write (lower WNM).

- The **threshold voltage** at which the latch flips defines the write margin.
- A higher WNM ensures easy data writing but can compromise read stability if access transistors become too dominant.
- The worst-case cell voltage during a write (which is found from measuring V1 when V2 is at 0V) is 208.376mV.

Proof for sizing

WA=100 nm, W_PD=160 nm, W_PU=200 nm, L=30 nm (28 nm)

1) MOSFET saturation equation

$$I_{D,sat} = \frac{1}{2} \mu C_{ox} \frac{W}{L} (V_{GS} - V_T)^2 (1 + \lambda V_{DS})$$

For first-order ratios, we take $\lambda \approx 0$ and define $\beta = \mu C_{ox} \frac{W}{L}$ so that

$$I_{D,sat} = \frac{1}{2} \beta V_{ov}^2, \quad V_{ov} = V_{GS} - V_T$$

2) Read stability (cell ratio CR)

Condition: $I_{PD} \geq I_A$ at equal V_{ov} .

$$\frac{I_{PD}}{I_A} = \frac{\beta_{PD}}{\beta_A} = \frac{(W/L)_{PD}}{(W/L)_A} = \frac{5.33}{3.33} \approx 1.60$$

3) Write-ability (access vs pull-up)

Condition: $\beta_A \cdot W_A > \beta_{PU} \cdot W_{PU}$

General ratio:

$$\frac{I_A}{I_{PU}} = \frac{\beta_A}{\beta_{PU}} \left(\frac{V_{ov,n}}{V_{ov,p}} \right)^2$$

$$\frac{I_A}{I_{PU}} \approx \frac{\mu_n}{\mu_p} \frac{(W/L)_A}{(W/L)_{PU}} \approx 2.5 \times \frac{3.33}{6.67} \approx 1.25$$